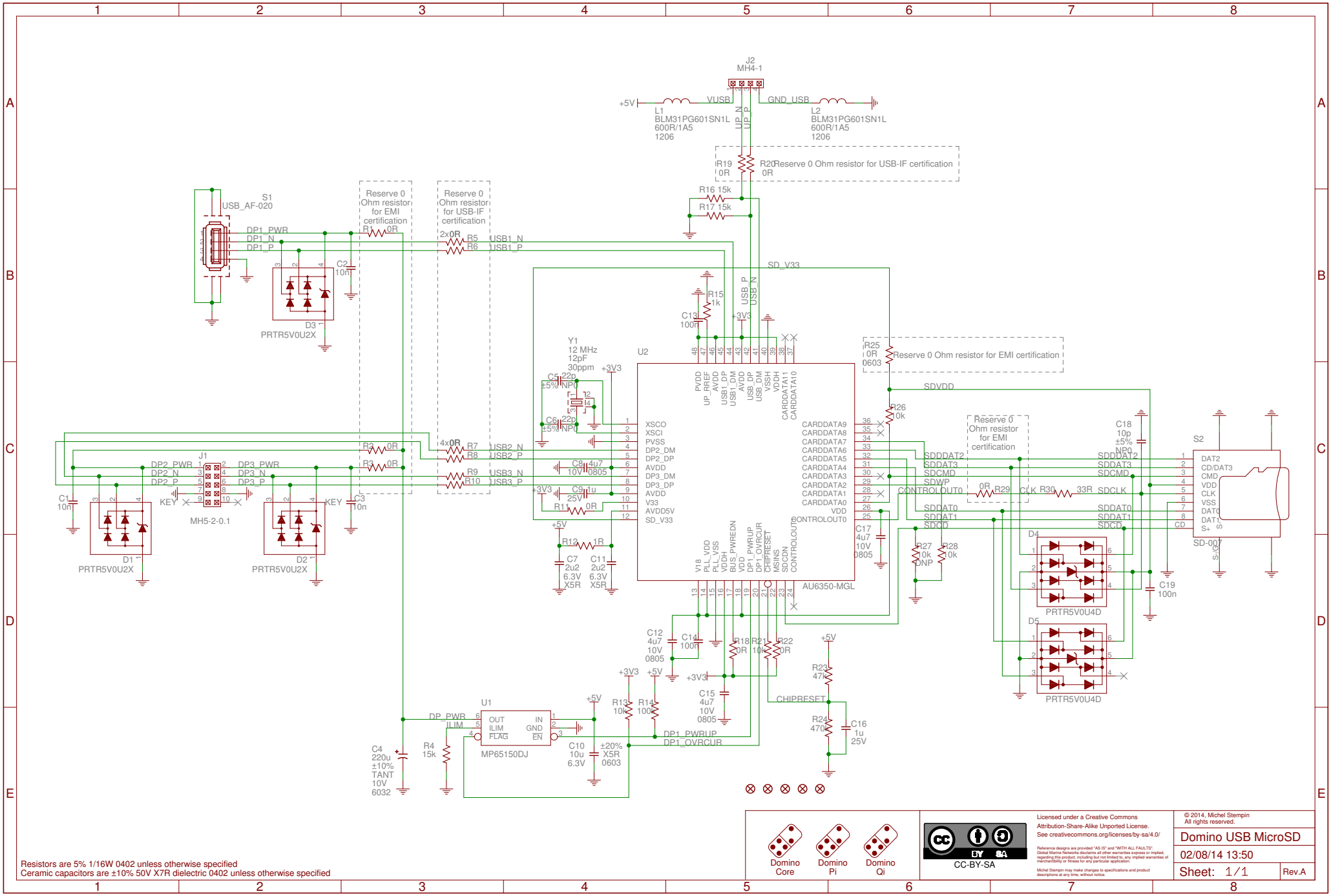


Resistors are 5% 1/16W 0402 unless otherwise specified
Ceramic capacitors are ±10% 50V X7R dielectric 0402 unless otherwise specified

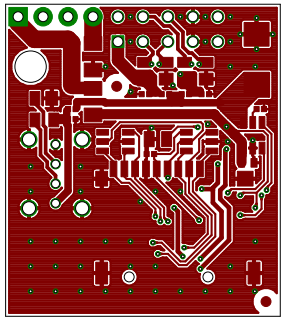
Domino Core
Domino Pi
Domino Qi

Domino USB MicroSD
02/08/14 13:50
Sheet: 1/1
Rev.A

LAYER-STACK

DRILL CHART: TOP TO BOTTOM

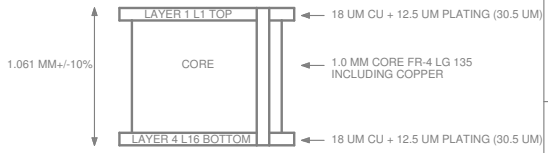
Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	77	YES
×	2	31	0.80	4	YES
◳	3	39	1.00	12	BOTH
◇	4	40	1.02	4	YES
⧖	5	53	1.35	4	YES
⋈	6	126	3.20	1	NOT



LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	90 Ohms	14.5 mils	6 mils	6 mils

STACK-UP FOR REFERENCE



NOTES:

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3. CIRCUIT PATHS ARE FOR REFERENCE ONLY.
4. HOLE SIZES SHOWN ARE FINISHED DIAMETERS AFTER PLATING.
5. BOARD PLATED USING REFLOW OR SIMILAR METHOD.
6. BOARD TO HAVE WHITE SOLDER MASK ON PLATED SURFACES USING WET FILM SR100 OR SR1010 EPOXY.
EQUIVALENT WET OR DRY FILM MAY BE USED.
7. SILKSCREEN BOARD USING BLACK INK. DISTORTION OF SILKSCREEN IS ACCEPTABLE OVER TRACES. EPOXY INK ON PLATED LANDS IS NOT ACCEPTABLE
8. THE FOLLOWING INFORMATION APPLIES TO THIS BOARD:
   * 2 COPPER LAYERS
   * 1 MM BOARD THICKNESS
   * REQUIRES TOP AND BOTTOM SIDE SILKSCREENS

Domino Core

Domino Pi

Domino Qi

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Domino USB MicroSD

02/08/14 18:59

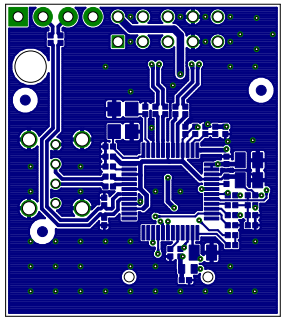
Component Side (.CMP)

Rev. A

LAYER-STACK

DRILL CHART: TOP TO BOTTOM

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	77	YES
×	2	31	0.80	4	YES
◳	3	39	1.00	12	BOTH
◇	4	40	1.02	4	YES
⧖	5	53	1.35	4	YES
⋈	6	126	3.20	1	NOT



LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B	
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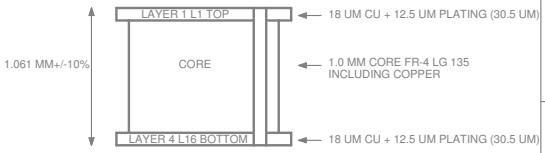

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Domino Core

Domino Pi

Domino Qi

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Domino USB MicroSD

02/08/14 18:59

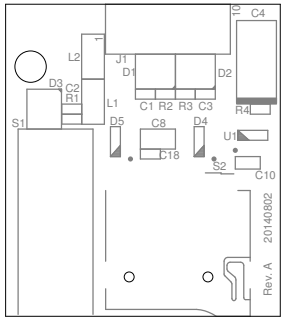
Solder side (.SOL)

Rev. A

LAYER-STACK

DRILL CHART: TOP TO BOTTOM

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	77	YES
×	2	31	0.80	4	YES
◳	3	39	1.00	12	BOTH
◇	4	40	1.02	4	YES
⧖	5	53	1.35	4	YES
⋈	6	126	3.20	1	NOT



LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
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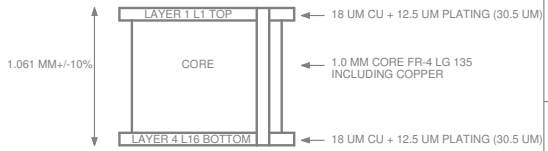

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Domino Qi

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Domino USB MicroSD

02/08/14 18:59

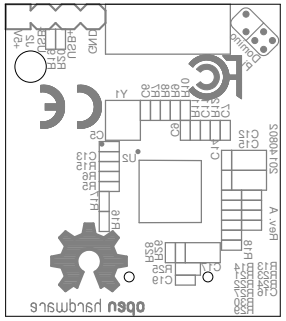
Silk screen CMP (.PLC)

Rev. A

LAYER-STACK

DRILL CHART: TOP TO BOTTOM

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	77	YES
×	2	31	0.80	4	YES
◳	3	39	1.00	12	BOTH
◇	4	40	1.02	4	YES
⧖	5	53	1.35	4	YES
⋈	6	126	3.20	1	NOT



LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B		
Layer	Impedance	Trace Width	Trace Separation	Ground Separation	
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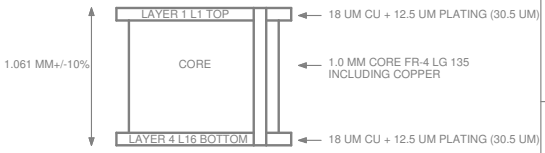

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Domino Core

Domino Pi

Domino Qi

Domino USB MicroSD

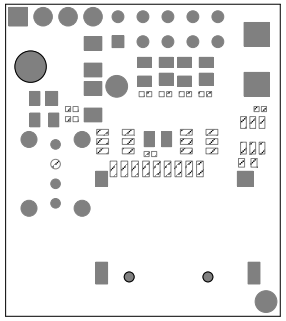
02/08/14 18:59

Silk screen SOL (.PLS) | Rev. A

LAYER-STACK

DRILL CHART: TOP TO BOTTOM

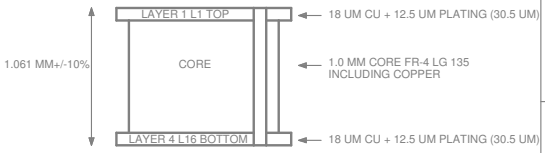
Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	77	YES
×	2	31	0.80	4	YES
◳	3	39	1.00	12	BOTH
◇	4	40	1.02	4	YES
⧖	5	53	1.35	4	YES
⋈	6	126	3.20	1	NOT



LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B		
Layer	Impedance	Trace Width	Trace Separation	Ground Separation	
TOP, BOTTOM	90 Ohms	14.5 mils	6 mils	6 mils	

STACK-UP FOR REFERENCE



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Domino Core

Domino Pi

Domino Qi

Domino USB MicroSD

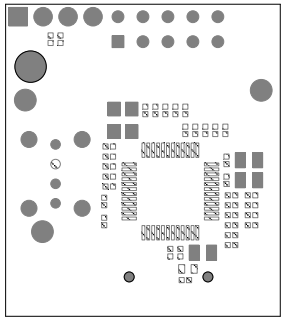
02/08/14 18:59

Solder stop mask CMP (.STC) | Rev. A

DRILL CHART: TOP TO BOTTOM

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	77	YES
×	2	31	0.80	4	YES
◳	3	39	1.00	12	BOTH
◇	4	40	1.02	4	YES
⧖	5	53	1.35	4	YES
⋈	6	126	3.20	1	NOT

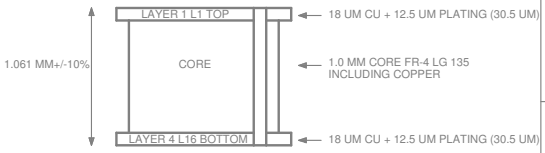
LAYER-STACK



LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B		
Layer	Impedance	Trace Width	Trace Separation	Ground Separation	
TOP, BOTTOM	90 Ohms	14.5 mils	6 mils	6 mils	

STACK-UP FOR REFERENCE



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Domino Core
Domino Pi
Domino Qi

Domino USB MicroSD

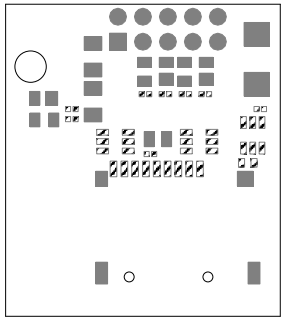
02/08/14 18:59

Solder stop mask SOL (.STS) | Rev. A

LAYER-STACK

DRILL CHART: TOP TO BOTTOM

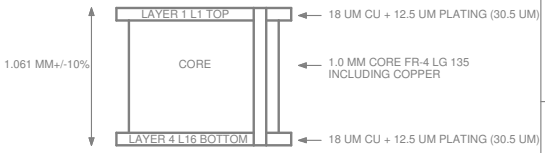
Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	77	YES
×	2	31	0.80	4	YES
◳	3	39	1.00	12	BOTH
◇	4	40	1.02	4	YES
⧖	5	53	1.35	4	YES
⋈	6	126	3.20	1	NOT



LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B		
Layer	Impedance	Trace Width	Trace Separation	Ground Separation	
TOP, BOTTOM	90 Ohms	14.5 mils	6 mils	6 mils	

STACK-UP FOR REFERENCE



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Domino Core

Domino Pi

Domino Qi

Domino USB MicroSD

02/08/14 18:59

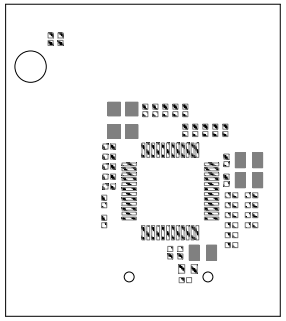
Cream frame CMP (.CRC)

Rev. A

DRILL CHART: TOP TO BOTTOM

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	77	YES
×	2	31	0.80	4	YES
◳	3	39	1.00	12	BOTH
◇	4	40	1.02	4	YES
⧖	5	53	1.35	4	YES
⋈	6	126	3.20	1	NOT

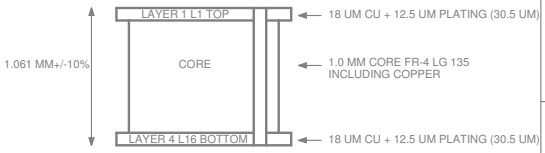
LAYER-STACK



LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B		
Layer	Impedance	Trace Width	Trace Separation	Ground Separation	
TOP, BOTTOM	90 Ohms	14.5 mils	6 mils	6 mils	

STACK-UP FOR REFERENCE



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Domino Core

Domino Pi

Domino Qi

Domino USB MicroSD

02/08/14 18:59

Cream frame SOL (.CRS)

Rev. A

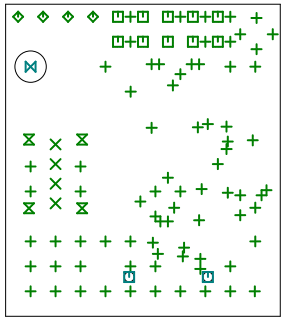
LAYER-STACK

01-16

01-20

DRILL CHART: TOP TO BOTTOM

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	77	YES
×	2	31	0.80	4	YES
◳	3	39	1.00	12	BOTH
◇	4	40	1.02	4	YES
⧖	5	53	1.35	4	YES
⋈	6	126	3.20	1	NOT



LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	90 Ohms	14.5 mils	6 mils	6 mils

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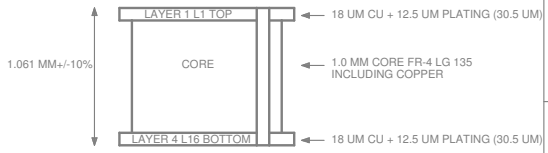

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Domino Core

Domino Pi

Domino Qi

Domino USB MicroSD

02/08/14 18:59

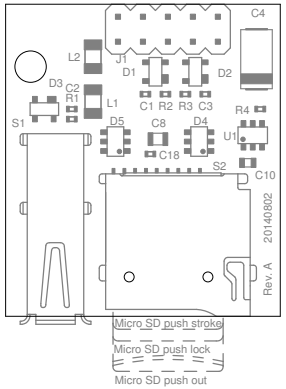
Drill data (.DRD)

Rev. A

LAYER-STACK

DRILL CHART: TOP TO BOTTOM

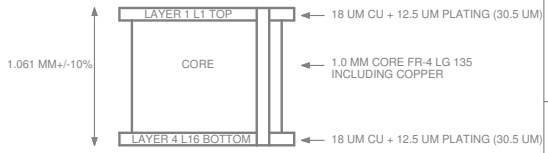
Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	77	YES
×	2	31	0.80	4	YES
◳	3	39	1.00	12	BOTH
◇	4	40	1.02	4	YES
⧖	5	53	1.35	4	YES
⋈	6	126	3.20	1	NOT



LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	90 Ohms	14.5 mils	6 mils	6 mils

STACK-UP FOR REFERENCE



NOTES:

1. PRINTED CIRCUIT BOARD MADE FROM NEMA GRADE FR-4 TG 135 EPOXY LAMINATE WITH 18 UM COPPER PLATING AND 1 MM THICKNESS.
2. ALL DIMENSIONS ARE GIVEN IN MILLIMETERS EXCEPT TRACE WIDTH/SPACE.
3. CIRCUIT PATHS ARE FOR REFERENCE ONLY.
4. HOLE SIZES SHOWN ARE FINISHED DIAMETERS AFTER PLATING.
5. BOARD PLATED USING REFLOW OR SIMILAR METHOD.
6. BOARD TO HAVE WHITE SOLDER MASK ON PLATED SURFACES USING WET FILM SR100 OR SR1010 EPOXY.
EQUIVALENT WET OR DRY FILM MAY BE USED.
7. SILKSCREEN BOARD USING BLACK INK. DISTORTION OF SILKSCREEN IS ACCEPTABLE OVER TRACES. EPOXY INK ON PLATED LANDS IS NOT ACCEPTABLE
8. THE FOLLOWING INFORMATION APPLIES TO THIS BOARD:
   * 2 COPPER LAYERS
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Domino Core

Domino Pi

Domino Qi

Domino USB MicroSD

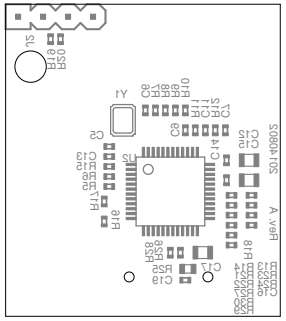
02/08/14 18:59

Component Assembly CMP (.ASC) | Rev. A

LAYER-STACK

DRILL CHART: TOP TO BOTTOM

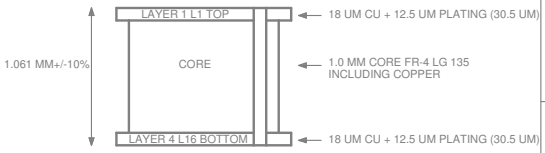
Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	77	YES
×	2	31	0.80	4	YES
◳	3	39	1.00	12	BOTH
◇	4	40	1.02	4	YES
⧖	5	53	1.35	4	YES
⋈	6	126	3.20	1	NOT



LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B		
Layer	Impedance	Trace Width		Trace Separation	Ground Separation
TOP, BOTTOM	90 Ohms	14.5 mils		6 mils	6 mils

STACK-UP FOR REFERENCE



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Domino USB MicroSD

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Component Assembly SOL (.ASS) | Rev. A

LAYER-STACK

DRILL CHART: TOP TO BOTTOM

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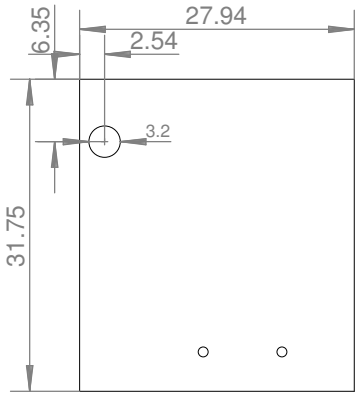

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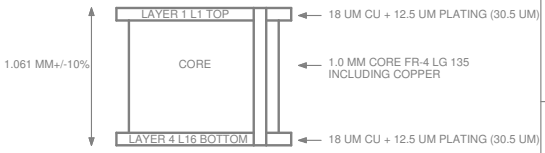

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Outline (.OLN) | Rev. A

LAYER-STACK

01-20

DRILL CHART: TOP TO BOTTOM

Sym	N°	Mils	MM	Qty	Plated
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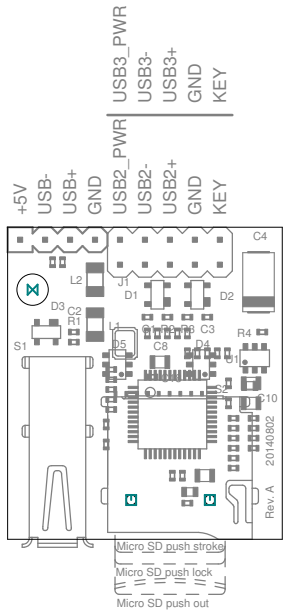

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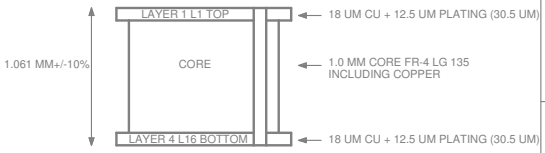

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Domino Qi

Domino USB MicroSD

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Pinout (.PIN)

Rev. A

Domino USB MicroSD Rev. A

Item	Qty	Value	Manufacturer	Device	Package	Reference	Description	Remarks
1	3	10n	ANY	C0402_10n_X7R_10%_CER_50V	C0402	C1, C2, C3	CAP CER 10000PF 50V 10% X7R 0402	
2	1	10u	ANY	C0603_10u_X5R_20%_CER_6V3	C0603	C10	CAP CER 10UF 6.3V 20% X5R 0603	
3	3	100n	ANY	C0402_100n_X7R_10%_CER_50V	C0402	C13, C14, C19	CAP CER 0.1UF 50V 10% X7R 0402	
4	1	10p	ANY	C0402_10p_NP0_5%_CER_50V	C0402	C18	CAP CER 10PF 50V 5% NP0 0402	
5	1	220u	ANY	CPOLC-6032_220u_20%_TANT_10V	C/6032-25	C4	CAP TANT 220UF 10V 20% 2413	
6	2	22p	ANY	C0402_22p_NP0_5%_CER_50V	C0402	C5, C6	CAP CER 22PF 50V 5% NP0 0402	
7	2	2u2	ANY	C0402_2u2_X5R_10%_CER_6V3	C0402	C7, C11	CAP CER 2.2UF 6.3V 20% X5R 0402	
8	4	4u7	ANY	C0805_4u7_X7R_10%_CER_6V3	C0805	C8, C12, C15, C17	CAP CER 4.7UF 6.3V 10% X7R 0805	
9	2	1u	ANY	C0402_1u_X7R_10%_CER_25V	C0402	C9, C16	CAP CER 1UF 25V 10% X7R 0402	
10	3	PRTR5V0U2X	NXP	PRTR5V0U2X	SOT143B	D1, D2, D3	TVS DIODE ARRAY 2CH 5V SOT143	
11	2	PRTR5V0U4D	NXP	PRTR5V0U4D	SOT23-6	D4, D5	TVS DIODE ARRAY 4CH 5V SOT23-6	
12	1	MH5-2-0.1	ANY	MH5-2-0.1	MH05-2-0.1	J1	CONN HEADER VERT .100 2ROWS 5POS 8.08 HEAD 3.05 TAIL 15AU	
13	1	MH4-1	ANY	MH4-1-0.1	MH4-1-0.1	J2	CONN HEADER VERT .100 1ROW 4POS 8.08 HEAD 3.05 TAIL 15AU	
14	2	BLM31PG601SN1L	MURATA	BLM31PG601SN1L	FB1206	L1, L2	FERRITE CHIP 600 OHM 1500MA 1206	
15	15	0R	ANY	R0402_0R_5%_62.5mW	R0402	R1, R2, R3, R5, R6, R7, R8, R9, R10, R11, R18, R19, R20, R22, R29	RES 0.0 OHM 1/16W JUMP 0402 SMD	
16	1	1R	ANY	R0402_1R_5%_62.5mW	R0402	R12	RES 1 OHM 1/16W JUMP 0402 SMD	
17	4	10k	ANY	R0402_10k_5%_62.5mW	R0402	R13, R21, R26, R27(DNP), R28	RES 10K OHM 1/16W 5% 0402 SMD	
18	1	100k	ANY	R0402_100k_5%_62.5mW	R0402	R14	RES 100K OHM 1/16W 5% 0402 SMD	
19	1	1k	ANY	R0402_1k_5%_62.5mW	R0402	R15	RES 1K OHM 1/16W 5% 0402 SMD	
20	1	47k	ANY	R0402_47k_5%_62.5mW	R0402	R23	RES 47K OHM 1/16W 5% 0402 SMD	
21	1	470k	ANY	R0402_470k_5%_62.5mW	R0402	R24	RES 470K OHM 1/16W 5% 0402 SMD	
22	1	0R	ANY	R0603_0R_5%_125mW	R0603	R25	RES 0.0 OHM 1/8W JUMP SMD 0603	
23	1	33R	ANY	R0402_33R_5%_62.5mW	R0402	R30	RES 33 OHM 1/16W 5% 0402 SMD	
24	3	15k	ANY	R0402_15k_5%_62.5mW	R0402	R4, R16, R17	RES 15K OHM 1/16W 5% 0402 SMD	
25	1	USB_AF-020	SZJUSTWELL ELECTRONICS	USB_AF-020	USB_AF-020	S1	CONN USB A RECPT T/H R/A VERT	
26	1	SD-007	SZJUSTWELL ELECTRONICS	SD-007	SD-007	S2	CONN MICRO SD R/A PUSH-PUSH SMD	
27	1	MP65150DJ	MONOLITHIC POWER	MP65150DJ	SOT23-6	U1	IC POWER SWITCH 1.7A SOT23-6	
28	1	AU6350-MGL	ALCOR MICRO	AU6350-MGL	LQFP-48_7X7	U2	IC 3-PORT USB HUB CARD COMBO CTRLR 48-LQFP	
29	1	12 MHz	ANY	CRYSTAL_32X25_2SH_12PF_30PPM	CRYSTAL_32X25	Y1	CRYSTAL 12MHZ 12PF 30PPM 3.2 X 2.5 SMD	